∴ Caution/Notice

⚠Caution

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⚠Caution

■ Storage and Operation Conditions

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. Also avoid exposure to moisture. Before cleaning, bonding or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed 5 to 40 degrees centigrade and 20 to 70%. Use capacitors within 6 months after delivery.

Rating

1. Operating Voltage

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the Vp-p value of the applied voltage or the V0-p which contains DC bias within the rated voltage range.

When the voltage is applied to the circuit, starting or stopping may generate irregular voltage for a transit period because of resonance or switching. Be sure to use a capacitor with a rated voltage range that includes these irregular voltages.

When DC-rated capacitors are to be used in input circuits from commercial power source (AC filter), be sure to use Safety Recognized Capacitors because various regulations on withstand voltage or impulse withstand established for all equipment should be taken into consideration.

Voltage	DC Voltage	DC+AC Voltage	AC Voltage	Pulse Voltage (1)	Pulse Voltage (2)
Positional Measurement	Vo-p	Vo-p	Vp-p	Vp-p	Vp-p

2. Operating Temperature and Self-generated Heat

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself. When the capacitor is used in a high-frequency current, pulse current or similar current, it may have self-generated heat due to dielectric loss. In the case of "High Dielectric Constant Type Capacitors," applied voltage load should be such that self-generated heat is within 20 °C under the condition where the capacitor is subjected at an atmosphere temperature of 25 °C. Please contact us if self-generated heat occurs with "Temperature Compensating Type Capacitors".

When measuring, use a thermocouple of small thermal capacity -K of Ø0.1mm under conditions where the capacitor is not affected by radiant heat from other components or wind from surroundings. Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.

3. Fail-Safe

Be sure to provide an appropriate fail-safe function on your product to prevent a second damage that may be caused by the abnormal function or the failure of our product.

⚠Caution



Continued from the preceding page.

■ Soldering and Mounting

1. Vibration and Impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

2. Soldering

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

3. Bonding, Resin Molding and Coating

In case of bonding, molding or coating this product, verify that these processes do not affect the quality of the capacitor by testing the performance of the bonded, molded or coated product in the intended equipment.

In case the amount of application, dryness/ hardening conditions of adhesives and molding resins containing organic solvents (ethyl acetate, methyl ethyl ketone, toluene, etc.) are unsuitable, the outer coating resin of a capacitor may be damaged by the organic solvents and may result, worst case, in a short circuit.

The variation in thickness of adhesive or molding resin or coating may cause an outer coating resin cracking and/or ceramic element cracking of a capacitor in a temperature cycling.

4. Treatment after Bonding, Resin Molding and Coating When the outer coating is hot (over 100 degrees centigrade) after soldering, it becomes soft and fragile, so please be careful not to give it mechanical stress.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.

■ Rating

1. Capacitance change of capacitor

In case of F/X7R/X7S/X7T/X8L/Y5V/Z5U char.

Capacitors have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor is left on for a long time. Moreover, capacitance might change greatly depending on the surrounding temperature or an applied voltage.

■ Soldering and Mounting

1. Cleaning (ultrasonic cleaning)

To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity: Output of 20 watts per liter or less.

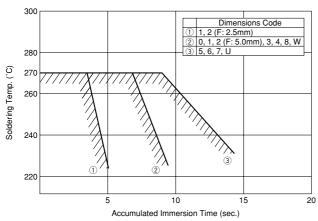
Rinsing time: 5 min. maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

2. Soldering and Mounting

(1) Allowable Conditions for Soldering Temperature and Time



Perform soldering within tolerance range (shaded portion).

(2) Insertion of the Lead Wire

- · When soldering, insert the lead wire into the PCB without mechanically stressing the lead wire.
- \cdot Insert the lead wire into the PCB with a distance appropriate to the lead space.

	Туре	Temperature Compensating Type	High Dielectric	Constant Type		
Pinantina	Rated Voltage	DC50V, DC100V	DC50V	DC100V		
Dimensions Code	Temp. Char.	X8G	X	BL		
0		8 102J	8 104K	8 103K		
1		U U	U D			
2		_	(M K58)	(M 224 K18		
3, W		_	(M 335 K58	_		
Temperature Char	acteristics	Marked with code (X8G, X8L char.: 8)				
Nominal Capac	citance	Marked with 3 figures				
Capacitance Tolerance		Marked with code				
Rated Voltage		Marked with code (DC50V: 5, DC100V: 1) A part is omitted (Please refer to the marking example.)				
Manufacturer's Ide	entification	Marked with M A part is omitted (Please refer to the marking example.)				

RH Series 150°C max. (for Automotive) Specifications and Test Methods

			Specifi	cation			
No.	AEC-Q200	Test Item	Temperature Compensating Type (Char. X8G)	High Dielectric Constant Type (Char. X8L)	AEC-Q200 Test Method		
1	Pre-and Pe			-	-		
	High Tem Exposure		The measured and observed characteristics should satisfy the specifications in the following table.				
		Appearance	No defects or abnormalities				
2		Capacitance Change	Within ±3% or ±0.3pF (Whichever is larger)	Within ±12.5%	Sit the capacitor for 1,000±12h at 150±3°C. Let sit for 24±2h at room temperature, then measure.		
		Q/D.F.	Q≥350	0.04 max.			
		I.R.	More than 1,000M Ω or 50M $\Omega \cdot \mu$	F (Whichever is smaller)			
	Temperati Cycling	ure	The measured and observed chaspecifications in the following tal	•	Perform the 1,000 cycles according to the four heat treatments listed in the following table. Let sit for 24±2h at *room condition,		
		Appearance	No defects or abnormalities excellent	ept color change of outer	Step 1 2 3 4		
3		Capacitance Change	Within ±5% or ±0.5pF (Whichever is larger)	Within ±12.5%	Temp. (°C) -55+0/-3 Room Temp. 150+3/-0 Room Temp. Time (min.) 15±3 1 15±3 1		
		Q/D.F.	Q≧350	0.05 max.	•Pretreatment Perform the heat treatment at 150+0/-10°C for 60±5 min and		
		I.R.	1,000M Ω or 50M Ω · μF min. (Wh	nichever is smaller)	then let sit for 24±2h at *room condition. (for Char. X8L)		
	Moisture Resistanc	The measured and observed character specifications in the following table.		•	Apply the 24h heat (25 to 65°C) and humidity (80 to 98%) treatment shown below, 10 consecutive times.		
		Appearance	No defects or abnormalities		Let sit for 24±2h at *room condition, then measure.		
		Capacitance Change	Within ±5% or ±0.5pF (Whichever is larger)	Within ±12.5%	Humidity Humidity Humidity Humidity Humidity (°C) 90-98% 80-98% 90-98% 80-98% 90-98% 70 65 6		
		Q/D.F.	Q≧200	0.05 max.	55 50 7		
4		I.R.	500M Ω or 25M Ω \cdot μF min. (Whice	chever is smaller)	9 45 40 40 40 40 40 40 40 40 40 40 40 40 40		
	Biased Hu	umidity	The measured and observed characteristics should satisfy the specifications in the following table.		Apply the rated voltage and DC1.3+0.2/-0V (add 6.8kΩ resistent 85±3°C and 80 to 85% humidity for 1,000±12h.		
		Appearance	No defects or abnormalities		Remove and let sit for 24±2h at *room condition, then measure.		
5		Capacitance Change	Within ±5% or ±0.5pF (Whichever is larger)	Within ±12.5%	The charge/discharge current is less than 50mA. •Pretreatment		
		Q/D.F.	Q≧200	0.05 max.	Perform the heat treatment at 150+0/-10°C for 60±5 min and		
		I.R.	500M Ω or 25M Ω · μF min. (Whice	chever is smaller)	then let sit for 24±2h at *room condition. (for Char. X8L)		
	Operation	al Life	The measured and observed chaspecifications in the following tal	,	Apply 150% of the rated voltage for 1,000±12h at 150±3°C.		
		Appearance	No defects or abnormalities except color change of outer coating		Let sit for 24±2h at *room condition, then measure. The charge/discharge current is less than 50mA.		
6		Capacitance Change	Within ±3% or ±0.3pF (Whichever is larger)	Within ±12.5%	Pretreatment Apply test voltage for 60±5 min at test temperature.		
		Q/D.F.	Q≧350	0.04 max.	Remove and let sit for 24±2h at *room condition. (for Char. X8L)		
		I.R.	1,000M Ω or 50M Ω · μF min. (Wi	nichever is smaller)	, ,		
7	External V	/isual	No defects or abnormalities		Visual inspection		
8	Physical [Dimension	Within the specified dimensions	<u> </u>	Using calipers and micrometers.		
9	Marking		To be easily legible.	-	Visual inspection		

^{* &}quot;room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmosphere pressure: 86 to 106kPa

Continued on the following page.

RH Series 150°C max. (for Automotive) Specifications and Test Methods

Continued from the preceding page.

	o. AEC-Q200 Test Item		Specification Temperature Compensating Type (Char. X8G) High Dielectric Constant Type (Char. X8L)				
No.					AEC-Q200 Test Method		
		Appearance	No defects or abnormalities		Per MIL-STD-202 Method 215		
		Capacitance	Within the specified tolerance		Solvent 1: 1 part (by volume) of isopropyl alcohol 3 parts (by volume) of mineral spirits		
10	Resistance	Q/D.F.	Q≥1,000	0.025 max.	Solvent 2: Terpene defluxer		
10	to Solvents	I.R.	More than 10,000MΩ or 500MΩ	υ·μF (Whichever is smaller)	Solvent 3: 42 parts (by volume) of water 1 part (by volume) of propylene glycol monomethyl ether 1 part (by volume) of monoethanolamine		
		Appearance	No defects or abnormalities		Three shocks in each direction should be applied along 3		
	Mechanical	Capacitance	Within the specified tolerance		mutually perpendicular axes of the test specimen (18 shocks		
1	Shock	Q/D.F.	Q≥1,000	0.025 max.	The specified test pulse should be Half-sine and should have a duration: 0.5ms, peak value: 1,500G and velocity change: 4.7m/s.		
		Appearance	No defects or abnormalities		The capacitor should be subjected to a simple harmonic moti		
		Capacitance	Within the specified tolerance		having a total amplitude of 1.5mm, the frequency being varie uniformly between the approximate limits of 10 and 2,000Hz.		
12	Vibration	Q/D.F.	Q≥1,000	0.025 max.	The frequency range, from 10 to 2,000Hz and return to 10Hz should be traversed in approximately 20min. This motion should be applied for 12 items in each 3 mutually perpendicular directions (total of 36 times).		
	Resistance to Soldering Heat		The measured and observed characteristics should satisfy the specifications in the following table.		The lead wire is immersed in the melted solder 1.5 to 2mm		
		Appearance	No defects or abnormalities		from the main body at 260±5°C for 10±1s. The specified iten		
13		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±7.5%	are measured after 24±2h.		
		Dielectric Strength (Between Terminals)			Pretreatment Perform the heat treatment at 150+0/-10°C for 60±5 min and then let sit for 24±2h at *room condition. (for Char. X8L)		
	Thermal S	Shock	The measured and observed characteristics should satisfy the specifications in the following table.		Perform the 300 cycles according to the two heat treatments listed in the following table (Maximum transfer time is 20s.).		
		Appearance	No defects or abnormalities		Let sit for 24±2h at *room condition, then measure.		
4		Capacitance	Within ±5% or ±0.5pF	Within ±12.5%	Step 1 2 Temp. (°C) -55+0/-3 150+3/-0		
		Change	(Whichever is larger)		Time (min.) 15±3 15±3		
		Q/D.F.	Q≧350	0.05 max.	•Pretreatment		
		I.R.	1,000M Ω or 50M Ω · μF min. (W	hichever is smaller)	Perform the heat treatment at 150+0/-10°C for 60±5min and then let sit for 24±2h at *room condition. (for Char. X8L)		
		Appearance	No defects or abnormalities		,		
		Capacitance	Within the specified tolerance				
15	ESD	Q/D.F.	Q≧1,000	0.025 max.	Per AEC-Q200-004		
		I.R.	More than 10,000M Ω or 500M Ω	· μF (Whichever is smaller)			
16			Lead wire should be soldered with uniform coating on the axial direction over 95% of the circumferential direction.		The terminal of a capacitor is dipped into a solution of ethanol (JIS-K-8101) and rosin (JIS-K-5902) (25%rosin in weight propotion) and then into molten solder (JIS-Z-3282) for 2±0.5 sec. In both cases the depth of dipping is up to about 1.5 to 2mm from the terminal body. Temp. of solder: 245±5°C Lead Free Solder (Sn-3.0Ag-0.5Cu) 235±5°C H60A or H63A Eutectic Solder		

^{* &}quot;room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmosphere pressure: 86 to 106kPa

Continued on the following page.

RH Series 150°C max. (for Automotive) Specifications and Test Methods

Continued from the preceding page.

7	Continued fro	om the prece	eding page.					
				Specif	ication			
No.	AEC-Q200	Test Item		mpensating Type . X8G)	High Dielectric Constant Type (Char. X8L)	AEC-Q200	Test Method	
		Appearance	No defects or a	bnormalities		Visual inspection.		
		Capacitance	Within the specified tolerance			The capacitance, Q/D.F. should be measured at 25°C at the		
		Q/D.F.	Q≧1,000		0.025 max.	X8G C≤1,000pF 1±0 X8G C>1000pF 1±0	quency Voltage 0.1MHz AC0.5 to 5V (r.m.s.) 0.1kHz AC1±0.2V (r.m.s.) 0.1kHz AC1±0.2V (r.m.s.)	
		Insulation Resistance	Room Temperature	10,000MΩ or 5 (Whichever is s	00MΩ · μF min. smaller)	The insulation resistance should DC voltage not exceeding the ratemperature and humidity and v (Charge/Discharge current ≤ 50	ated voltage at normal vithin 2min. of charging.	
17		(I.R.)	High Temperature	100M Ω or 5M Ω (Whichever is s		The insulation resistance should a DC voltage not exceeding the temperature and humidity and v (Charge/Discharge current ≤ 50	rated voltage at normal within 2min. of charging.	
	Between Terminals No defects or abnormalities		The capacitor should not be damaged when DC voltage of 300% of the rated voltage (for Char. X8G) or DC voltage o 250% of the rated voltage (for Char. X8L) is applied betwee the terminations for 1 to 5 seconds. (Charge/Discharge current ≤ 50mA.)					
		Dielectric Strength			bnormalities	The capacitor is placed in a conwith metal balls of 1mm diameted that each terminal, short-circuit approximately 2mm from the ball and 250% of the rated DC volta impressed for 1 to 5 seconds between capacitor terminals and metal balls. (Charge/Discharge current ≤ 50)	er so is kept alls, ige is Approx. 2mr	
18	Terminal	Tensile Strength	Termination no	t to be broken or	loosened	As in the figure, fix the capacito apply the force gradually to eac in the radial direction of the cap until reaching 10N and then kee force applied for 10±1 seconds.	th lead acitor pp the	
	Strength	Bending Strength	Termination no	t to be broken or	loosened	Each lead wire should be subject be bent 90° at the point of egreet then returned to the original post opposite direction at the rate of	ss in one direction. Each wire is sition and bent 90° in the	
						The capacitance change should each specified temperature step		
						Step	Temperature (°C)	
			Within the en-	sified		1	25±2	
			Within the spect Tolerance.	Jilleu		2 3	-55±3 25±2	
	Capacitar	nce	(Table A)		Within ±15%	4	150±3	
19 1	1 .				(Temp. Range: -55 to +125°C)	5	25±2	
	Character	Characteristics Canacitance Drift is within		Within +15/-40% (Temp. Range: +125 to +150°C)	The temperature coefficient or t change is determined using the step 3 as a reference. •Pretreatment Perform the heat treatment at then let sit for 24±2h at *room Perform the initial measureme	capacitance measured in 150+0/-10°C for 60±5 min and condition.		

 $^{^{\}star}$ "room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmosphere pressure: 86 to 106kPa

Table A

	Nominal Values	Capacitance Change from 25°C (%)						
Char.		−55°C		−30°C		−10°C		
	(ppm/°C) *	Max.	Min.	Max.	Min.	Max.	Min.	
YAG	0+30	0.58	_0 24	0.40	_0.17	0.25	_0.11	

^{*} Nominal values denote the temperature coefficient within a range of 25°C to 150°C.

Packaging

Two types of packaging for monolithic ceramic capacitors are available.

1. Bulk Packaging

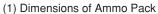
Minimum Quantity

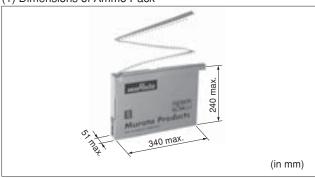
Dimensions Code	Dimensions (LXW)	Minimum Quantity (pcs./Bag)*
0	3.6×3.5mm or 4.0×3.5mm or 5.0×3.5mm (Depends on Part Number)	
1	4.0×3.5mm or 4.5×3.5mm or 5.0×3.5mm (Depends on Part Number)	
2	5.0×3.5mm or 5.5×4.0mm or 5.7×4.5mm (Depends on Part Number)	
3	5.0×4.5mm or 5.5×5.0mm or 6.0×5.5mm (Depends on Part Number)	500
4	7.5×5.5mm	500
5	7.5×7.5mm or 7.5×8.0mm (Depends on Part Number)	
6	10.0×10.0mm	
8	7.5×5.5mm	
7	12.5×12.5mm	100
U	7.7×12.5mm or 7.7×13.0mm (Depends on Part Number)	200
W	5.5×7.5mm or 6.0×8.0mm (Depends on Part Number)	500

Please order with an integral multiple of the minimum quantity above.

Please check our website 'Product details'.

2. Tape Carrier Packaging





(2) Minimum Quantity

Dimensions Code	Dimensions (LXW)	Minimum Quantity (pcs./Ammo Pack)*
0	3.6×3.5mm or 4.0×3.5mm or 5.0×3.5mm (Depends on Part Number)	
1	4.0×3.5mm or 4.5×3.5mm or 5.0×3.5mm (Depends on Part Number)	
2	5.0×3.5mm or 5.5×4.0mm or 5.7×4.5mm (Depends on Part Number)	2000
3	5.0×4.5mm or 5.5×5.0mm or 6.0×5.5mm (Depends on Part Number)	
4	7.5×5.5mm	
5	7.5×7.5mm or 7.5×8.0mm (Depends on Part Number)	2000
6	10.0×10.0mm	1500
8	7.5×5.5mm	1500
U	7.7×12.5mm or 7.7×13.0mm (Depends on Part Number)	1000
W	5.5×7.5mm or 6.0×8.0mm (Depends on Part Number)	1500

Please order with an integral multiple of the minimum quantity above.

Please check our website 'Product details'.

"Minimum Quantity" means the numbers of units of each delivery or order. The quantity should be an integral multiple of the "minimum quantity". (Please note that the actual delivery quantity in a package may change sometimes.)

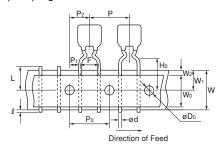
^{*} Minimum Quantity may change depends on part number.

st Minimum Quantity may change depends on part number.

 $\begin{tabular}{|c|c|c|c|c|c|}\hline \end{tabular}$ Continued from the preceding page.

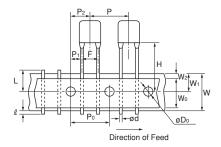
■ Taping Dimensions

Inside Crimp Taping



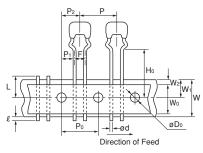
B: : II IOI I O I
Dimensions and Lead Style Code
0M1
1M1
2M1
2M2
3M1
3M2
4M1
4M2
8M1
8M2
WM1

Straight Taping

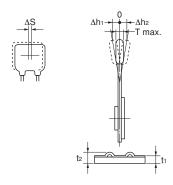


Dimensions and Lead Style Code
1DB
2DB
3DB
5E1
5E2
6E1
6E2
UE1

Outside Crimp Taping



Dimensions and Lead Style Code
0\$1
1\$1
2\$1
2\$2
3S1
3S2



		_		
Item	Code	Dim	nensions (mm)	
Pitch of Component	Р	12.7±1.0		
Pitch of Sprocket Hole	P ₀		12.7±0.2	
Lead Spacing	F	2.5 +0):4 (DB) (S1) (S2)	
Lead Spacing			5.0 + 0.6 -0.2	
Length from Hole Center to Component Center	P ₂		6.35±1.3	
	P ₁		3.85±0.7	
Length from Hole Center to Lead	F1	5.1±0	.7 (DB) (S1) (S2)	
Loud	254±1.5	5 Total length	of components pitch \times 20	
Body Dimension	[Depends o	n Part Number	
Deviation Along Tape, Left or Right Defect	ΔS		±2.0	
Carrier Tape Width	W	18.0±0.5		
Position of Sprocket Hole	W ₁	9.0+0		
Lead Distance between	Нο	16.0±0.5 (M1) (S1)		
Reference and Bottom Plane	Пυ	20.0±0.5 (M2) (S2)		
For Straight Lead Type	Н	20±0.5 (E2),	17.5±0.5 (E1),16±0.5 (DB)	
Diameter of Sprocket Hole	D ₀		4.0±0.1	
Lead Diameter	d		0.5±0.05	
Total Tape Thickness	t1		0.6±0.3	
Total Thickness of Tape and Lead Wire	t2		1.5 max.	
Body Thickness	Т	Depend	ds on Part Number	
		2.0 max.	Dimensions Code: W, U	
Deviation Across Tape	Δh1 Δh2	1.5 max.	RHD Series	
		1.0 max.	except as above	
Portion to Cut in Case of Defect	L	11.0 +0		
Protrusion Length	l	0.5 max.		
Hold Down Tape Width	Wo	9.5 min.		
Hold Down Tape Position	W ₂	1.5±1.5		
Coating Extension		Depends o	n Dimensions	

单击下面可查看定价,库存,交付和生命周期等信息

>>Murata(村田)